ABSTRACT OF THE DISCLOSURE

This invention relates to a method of creating an electrically conducting bonding between a face of a first semi-conductor element (10) and a face of a second semi-conductor element (12) using heat treatment. The method consists of :

- applying said faces one against the other with the placing between them of at least one layer (11, 15, 16, 13) of a material intended to provide, after heat treatment, an electrically conducting bonding between the two faces, the deposited layers being chosen so that the heat treatment does not induce any reaction product between said material and the semi-conductor elements (10, 12),

- carrying out said heat treatment.

Fig. 1C

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